

AFE159x Low-Power, 4-Channel, 24-Bit Analog Front-Ends for Bio-Potential Measurements

1 Features

- Integrated Signal Chain for ECG, Pace Detection, and Respiration Measurement
- **ECG Receiver**
 - Four high resolution channels at low power of 0.42mW/channel
 - Flexible four leads selectable from six electrodes
 - Programmable gain: 1.25 to 9
 - Input-referred noise: $4\mu\text{V}_{\text{PP}}$ in 150Hz BW
 - Differential input range: $\pm 1\text{V}$ with Gain = 4
 - CMRR: -140dB
 - Data rate: 125SPS to 128kSPS
- **Pace Detection**
 - On-chip digital pace detection algorithm on programmable two leads
 - High-speed 128kSPS pace output on two channels for software pace detection
- **Respiration**
 - Low-noise of $24\text{m}\Omega_{\text{PP}}$ with $2\text{k}\Omega$ body impedance and $1\text{k}\Omega$ defibrillator protection resistor on each electrode
 - Supports Sine and Square wave excitation
- **Other Features**
 - Built-in right leg drive amplifier steerable to any electrode
 - DC lead-off detection, AC lead impedance detection, Wilson Center Terminal (WCT), Goldberger Central Terminals (GCT), test signals
 - Battery voltage monitoring
 - Flexible power-down and standby modes
 - Built-in oscillator, PLL, and reference
 - 1k sample main FIFO and 2k sample pace FIFO
 - SPI-compatible serial interface
 - Analog supply voltage 1: 3.15V to 5.25V
 - Analog supply voltage 2: 1.7V to 1.9V
 - I/O supply voltage: 1.65V to 3.6V
- Supports systems meeting AAMI EC11, AMI EC13, AMI EC38, IEC60601-1, IEC60601-2-25, IEC60601-2-27, and IEC60601-2-51 standards

2 Applications

- Medical instrumentation (ECG, EMG, and EEG):
 - Bedside patient monitoring and diagnostic ECG
 - Portable telemetry
 - Holter monitor and multi-lead patch
- Event, stress, and vital sign monitors:
 - ECGs
 - AEDs
 - Telemedicine Bispectral Index (BIS)
 - Evoked Audio Potential (EAP)
 - Sleep study monitor

3 Description

The AFE1594 is a family of multichannel, simultaneous sampling, 24-bit, delta-sigma ($\Delta\Sigma$) analog-to-digital converters (ADCs) with built-in programmable gain Instrumentation Amplifiers (INAs), internal reference, and an on-chip PLL. The AFE supports digital pace pulse detection, thoracic impedance measurement and incorporates all of the features that are commonly required in medical electrocardiogram (ECG) and electroencephalogram (EEG) applications. Multiple AFE159x devices can be cascaded in high channel count systems. With high levels of integration and exceptional performance, the AFE159x enables the development of scalable medical instrumentation systems at significantly reduced size, power, and overall cost.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾
AFE1594	QFN	7mm × 7mm
AFE1593/AFE1594	WCSP	3.7mm × 3.7mm

- (1) For all available packages, see Mechanical, Packaging, and Orderable Information.
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.



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4 Device Comparison

Table 4-1. Comparison of the features between the AFE159x variants

	AFE159RP3	AFE159RP4	AFE159P4	AFE1594
Number of ECG electrode pins	6	6	6	6
Number of ECG channels	3	4	4	4
Number of Respiration electrode pins	4	3/4 ⁽¹⁾	3/4 ^{(1) (2)}	3/4 ^{(1) (2)}
Number of Respiration receiver channel	1	1	-	-
Number of internal Pace detect channels	1	2	2	-

(1) 4 electrodes supported in WCSP package.

(2) Only RESP_OUT pins available, RESP_IN pins are NC.

5 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

5.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

5.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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5.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.
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5.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

6 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (June 2024) to Revision A (July 2024)	Page
• Updated device status to Production Data.....	1

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
AFE159RP4RGZR	ACTIVE	VQFN	RGZ	48	2500	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-20 to 85	AFE159RP4	Samples
AFE159RP4RGZT	ACTIVE	VQFN	RGZ	48	250	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-20 to 85	AFE159RP4	Samples
PAFE159RP4RGZR	ACTIVE	VQFN	RGZ	48	2500	TBD	Call TI	Call TI	-20 to 85		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AFE159RP4RGZR	VQFN	RGZ	48	2500	330.0	16.4	7.3	7.3	1.1	12.0	16.0	Q2
AFE159RP4RGZT	VQFN	RGZ	48	250	180.0	16.4	7.3	7.3	1.1	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
AFE159RP4RGZR	VQFN	RGZ	48	2500	367.0	367.0	35.0
AFE159RP4RGZT	VQFN	RGZ	48	250	210.0	185.0	35.0

GENERIC PACKAGE VIEW

RGZ 48

VQFN - 1 mm max height

7 x 7, 0.5 mm pitch

PLASTIC QUADFLAT PACK- NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

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